

IRM-H5XXT/TR2 series

Parts Table

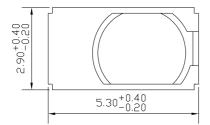
Standard Application Type			
Model No.	Carrier Frequency		
IRM-H538T/TR2	38 kHz		



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Package Dimenstions

(Dimensions in mm)

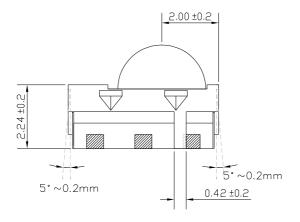


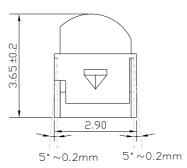
Pin Function

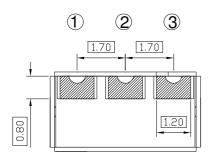
 $(1):V_{out}$

2:V cc

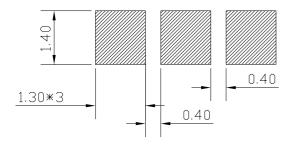
③:GND







Recommended pad layout for surface mount leadform





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Absolute Maximum Ratings (T_a=25 °C)

Parameter	Symbol	Rating	Unit
Supply Voltage	Vs	6	V
Operating Temperature	Topr	-25 ~ +80	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Soldering Temperature	Tsol	260	$^{\circ}\!\mathbb{C}$

Electro-Optical Characteristics (Ta=25℃ and Vcc=3.0V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Current Consumption	Icc	-	1.0	1.2	mA	No signal input
Supply Voltage	Vs	2.7	-	5.5	V	
Peak Wavelength	λ_{p}	-	940	-	nm	
Reception Distance	L ₀	8	-	-		See chapter ,Test method'
	L ₄₅	5	-	-	m	
High Level Pulse Width	T _{wh}	400	-	800	μs	Test signal
Low Level Pulse Width	T _{WL}	400	-	800	μs	according to figure 1
High Level Output Voltage	V _H	Vcc-0.4	-	-	V	I _{SOURCE} ≦1μΑ
Low Level Output Voltage	V _L	-	-	0.5	V	I _{SINK} ≦2mA



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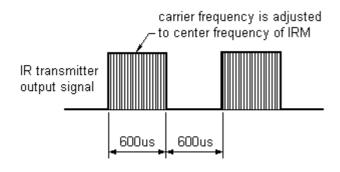
Test Method

The specified electro-optical characteristic is satisfied under the following Conditions:

- 1. Measurement environment
 - A place without extreme light reflected
- 2. External light
 - Ordinary white fluorescent lamps (Light source temperature 2856 °K, Ee ≤ 10Lux) without high frequency modulation
- 3. Standard transmitter
 - The test transmitter is calibrated by using the circuit shown in figure 2. The radiation intensity of the transmitter is adjusted until **Vo=400mVp-p.** Both, the test transmitter and the photo diode, have a peak wavelength of 940nm. The photo diode for calibration is PD438B (λp=940nm, Vr=5V).
- 4. Measuring system According to the measuring system shown in Fig.-3

Fig.-1 Transmitter Wave Form

D.U.T output Pulse



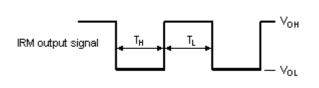


Fig.-2 Measuring Method

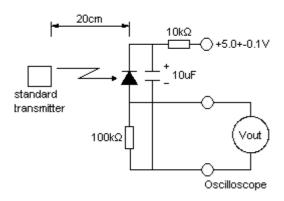
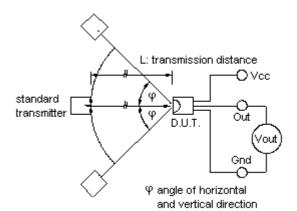


Fig.-3 Measuring System





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Typical Performance Curves

Fig.-4 Relative Spectral Sensitivity vs. Wavelength

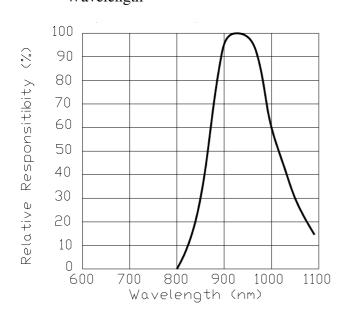


Fig.-5 Relative Transmission Distance vs. Direction

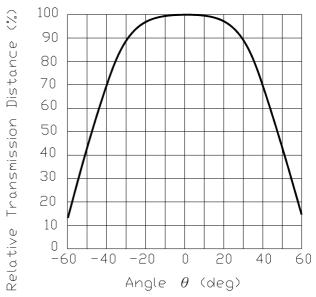
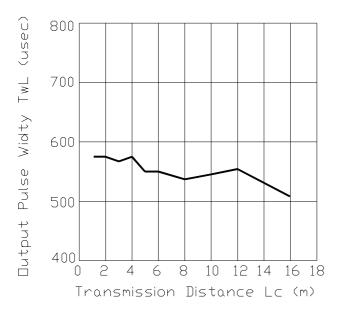
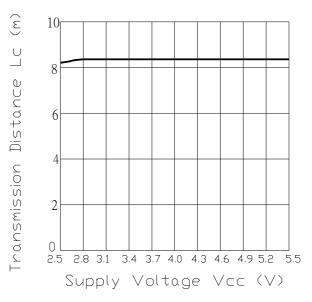


Fig.-6 Output Pulse Length vs. Arrival Distance Fig.-7 Arrival Distance vs. Supply Voltage

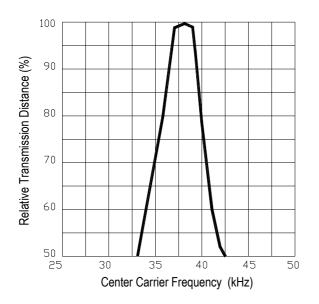


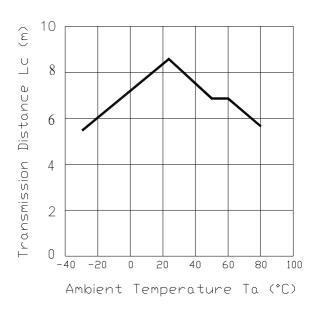




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Fig.-8 Relative Transmission Distance vs. Center Fig.-9 Arrival Distance vs. Ambient Temperature Carrier Frequency







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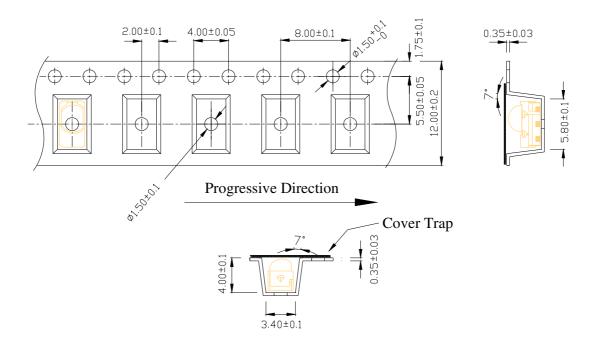
Code information

Protocol	Suitable	Protocol	Suitable
JVC	No	RCA	No
Matsushita	Yes	Sharp	Yes
Mitsubishi	No	Sony 12 Bit	Yes
NEC	Yes	Sony 15 Bit	No
RC5	Yes	Sony 20Bit	No
RC6	Yes	Toshiba	Yes
RCMM	No	Zenith	Yes
RCS-80	No	Continuous Code	No



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Tape & Reel Packing Specifications



Packing Quantity

1000 pcs / Reel

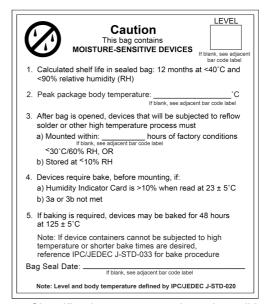
5 Reels / Carton



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Label format





Moisture Classification-storage and used condition label

Recommended method of storage

The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- 1. Shelf life in sealed bag from the bag seal date: 12 months at < 40 ℃ and < 90% relative humidity (RH)
- 2. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must mounted within 72 hours of factory conditions < 30 °C/60%RH.
- 3. If the moisture absorbent material (silica gel) has faded away or the IRM has exceeded the storage time. Baking treatment is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the conditions: 60±5°C for 96 hours.

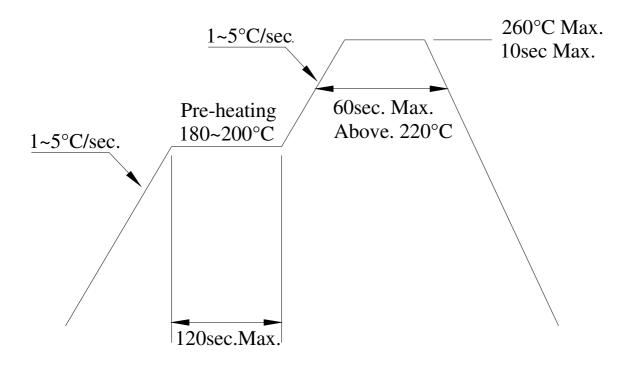
ESD Precaution

Proper storage and handing procedures should be followed to prevent ESD damage to the devices especially when they are removed from the Anti-static bag. Electro-Static Sensitive Devices warning labels are on the packing.



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Solder Reflow Temperature Profile



Note:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the IRM device during heating.
- 3. After soldering, do not warp the circuit board.



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- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for use outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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